



# NPD15N10

N-Ch 100V Fast Switching MOSFETs

## General Description

The NPD15N10 is the highest performance trench N-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The NPD15N10 meet the RoHS and Green requirement with full ~~Photo~~reliability approved.

## Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	14.7	A
$I_D @ T_C = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	13.6	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	59	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation <sup>3</sup>	50	W
$P_D @ T_C = 70^\circ C$	Total Power Dissipation <sup>3</sup>	32	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

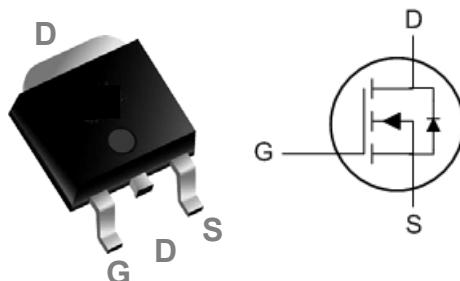
## Product Summary

BVDSS	RDS(on)	ID
100V	145mΩ	15A

## Applications

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Power Tool Application

## TO252 Pin Configuration



## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	---	3.6	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	50	°C/W

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	100	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=6\text{A}$	---	100	145	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=5\text{A}$	---	150	195	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.0	1.6	3.0	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	-4.12	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
			---	---	---	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $b=6\text{A}$	---	5	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	2.5	5	$\Omega$
$Q_g$	Total Gate Charge (10V)	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=6\text{A}$	---	7.8	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	1.3	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	2.9	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$	---	9.8	---	ns
$T_r$	Fall Time		---	10.2	---	
$T_{\text{d(off)}}$	Rise Time		---	18	---	
$T_f$	Turn-Off Delay Time		---	8.5	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	480	---	pF
$C_{\text{oss}}$	Output Capacitance		---	47	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	29	---	

## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_S=1\text{A}$ , $T_J=25^\circ\text{C}$	---	0.775	1.3	V

## Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



## Typical Characteristics

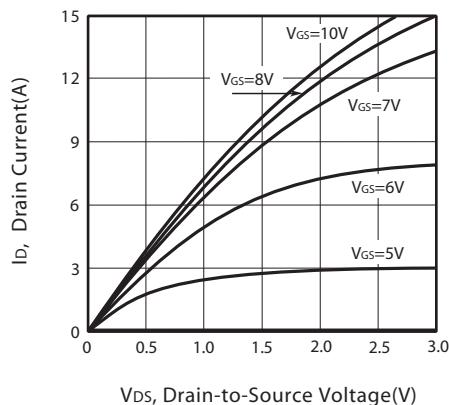


Figure 1. Output Characteristics

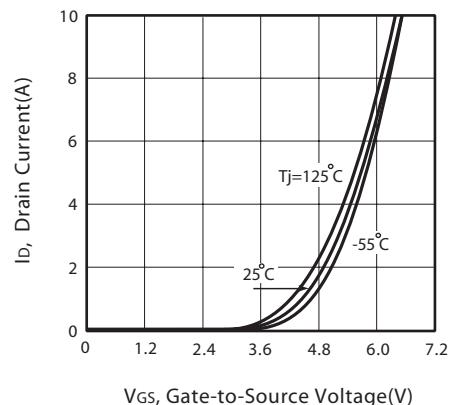


Figure 2. Transfer Characteristics

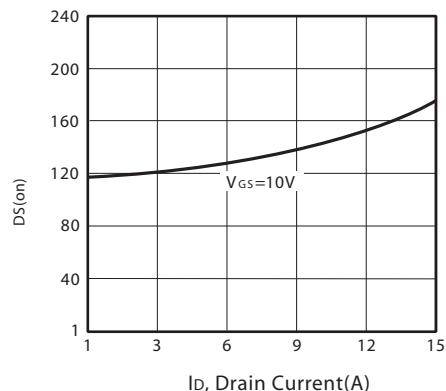
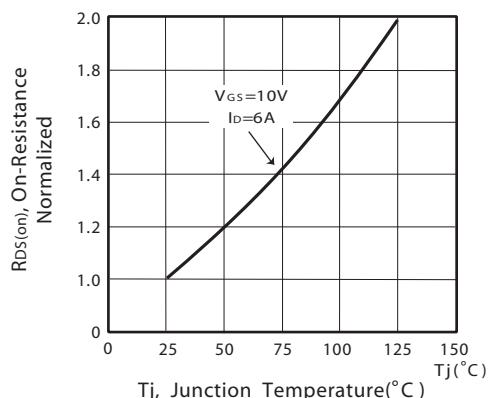


Figure 3. On-Resistance vs. Drain Current and Gate Voltage



Current and Temperature

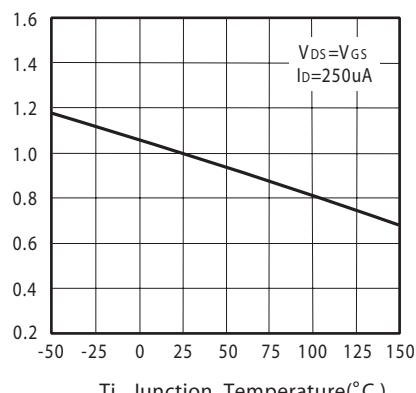


Figure 5. Gate Threshold Variation with Temperature

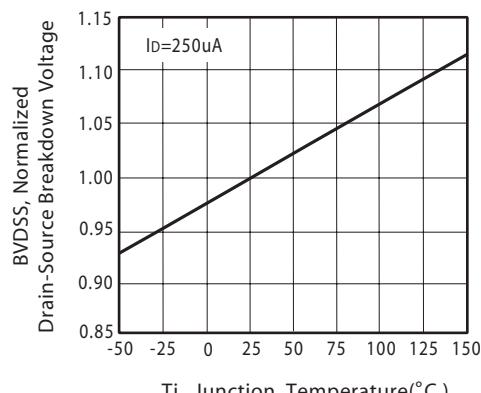
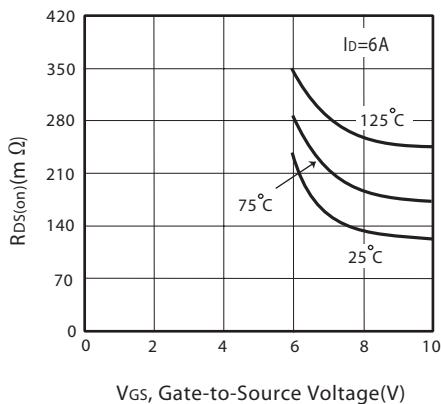
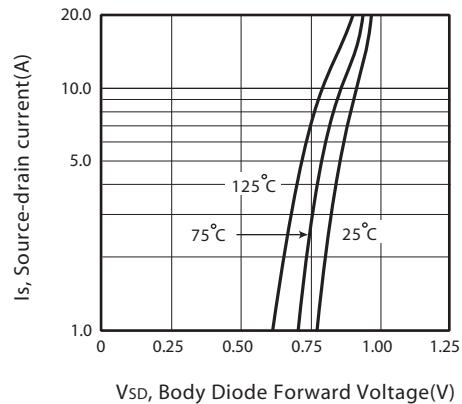


Figure 6. Breakdown Voltage Variation with Temperature



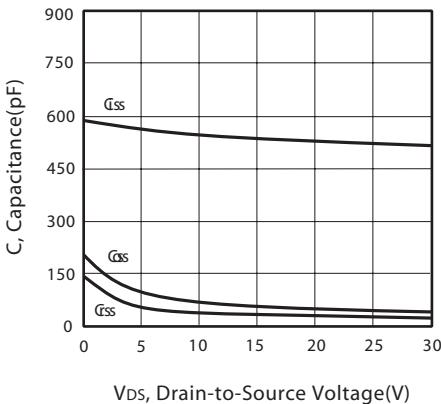
V<sub>GS</sub>, Gate-to-Source Voltage(V)

Figure 7. On-Resistance vs. Gate-Source Voltage



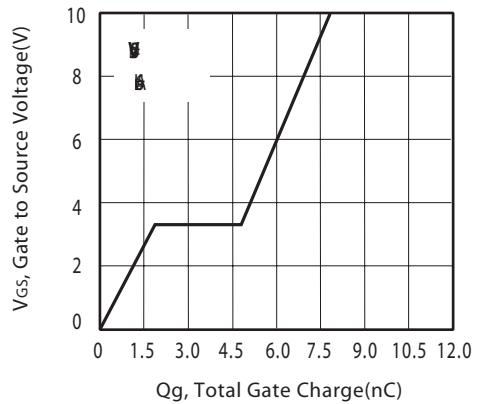
I<sub>S</sub>, Source-drain current(A)

Figure 8. Body Diode Forward Voltage Variation with Source Current



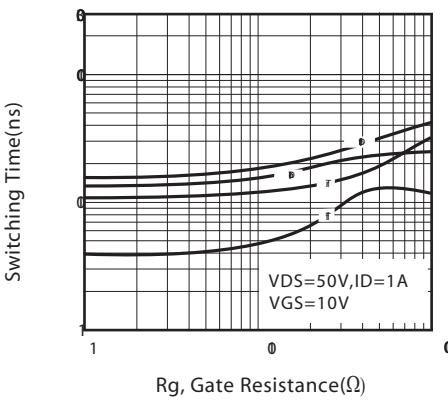
V<sub>DS</sub>, Drain-to-Source Voltage(V)

Figure 9. Capacitance

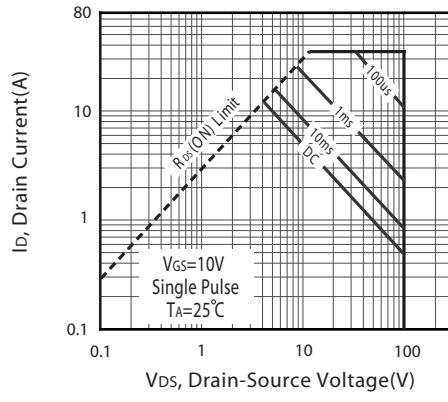


Q<sub>g</sub>, Total Gate Charge(nC)

Figure 10. Gate Charge



R<sub>g</sub>, Gate Resistance(Ω)



I<sub>D</sub>, Drain Current(A)

V<sub>DS</sub>, Drain-Source Voltage(V)